

**AMENDMENTS TO THE CLAIMS**

Claims 1-5 (Canceled)

Claim 6 (New)      An integrated circuit arrangement comprising a nonplanar substrate on which an integrated circuit is formed on at least one side, wherein the at least one side is arranged on a carrier, and the carrier is produced from a chemically resistant material.

Claim 7 (New)      The integrated circuit arrangement as claimed in claim 6, wherein the chemically resistant material of the carrier is formed from ceramic.

Claim 8 (New)      The integrated circuit arrangement as claimed in claim 7, wherein a side of the carrier which is remote from the integrated circuit has a planar surface.

Claim 9 (New)      The integrated circuit arrangement as claimed in claim 8, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 10 (New)     The integrated circuit arrangement as claimed in claim 9, wherein the carrier has a cavity in which the substrate is completely held.

Claim 11 (New)     The integrated circuit arrangement as claimed in claim 8, wherein the carrier has a cavity in which the substrate is completely held.

Claim 12 (New)     The integrated circuit arrangement as claimed in claim 7, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 13 (New)      The integrated circuit arrangement as claimed in claim 12, wherein the carrier has a cavity in which the substrate is completely held.

Claim 14 (New)      The integrated circuit arrangement as claimed in claim 7, wherein the carrier has a cavity in which the substrate is completely held.

Claim 15 (New)      The integrated circuit arrangement as claimed in claim 6, wherein a side of the carrier which is remote from the integrated circuit has a planar surface.

Claim 16 (New)      The integrated circuit arrangement as claimed in claim 15, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 17 (New)      The integrated circuit arrangement as claimed in claim 16, wherein the carrier has a cavity in which the substrate is completely held.

Claim 18 (New)      The integrated circuit arrangement as claimed in claim 15, wherein the carrier has a cavity in which the substrate is completely held.

Claim 19 (New)      The integrated circuit arrangement as claimed in claim 6, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 20 (New)      The integrated circuit arrangement as claimed in claim 19, wherein the carrier has a cavity in which the substrate is completely held.

Claim 21 (New)      The integrated circuit arrangement as claimed in claim 6, wherein the carrier has a cavity in which the substrate is completely held.

Claim 22 (New)      An integrated circuit arrangement comprising a curved substrate having an integrated circuit formed on the outer side thereof, wherein the outer side is arranged on a carrier, and the carrier is produced from a chemically resistant material.

Claim 23 (New)      The integrated circuit arrangement as claimed in claim 22, wherein the chemically resistant material of the carrier is formed from ceramic.

Claim 24 (New)      The integrated circuit arrangement as claimed in claim 22, wherein a side of the carrier which is remote from the integrated circuit has a planar surface.

Claim 25 (New)      The integrated circuit arrangement as claimed in claim 22, wherein the entire area of the outer side of the curved substrate is connected to the carrier.

Claim 26 (New)      The integrated circuit arrangement as claimed in claim 22, wherein the carrier has a cavity in which the curved substrate is completely held.